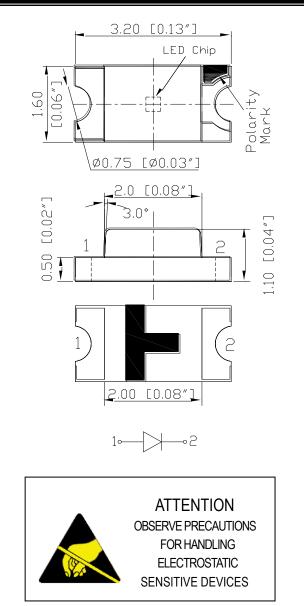
S150 Series SMD Chip LED Lamps

Part Number: N0A24S29

Package outlines



RECOMMEN	ID PAD LAYOUT	
<u>1.50</u> <u>2.0[0</u> [0.06″]		E0.06 *]
ITEM	MATERIALS	
Resin (mold)	Ероху	
Bonding Wire	Ø 25 μm Au	
Lens color	Water transparent	
Printed circuit board	BT (white)	
Dice	AlGaInP/GaAs	

Amber

NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are $\pm 0.1 \text{mm}$ (0.004inch) unless otherwise noted.

Rev :	Date	Drawn by :	Checked by :	Approved by :
A	2010/10/12	李梅英	許媚鳳	黄靜文

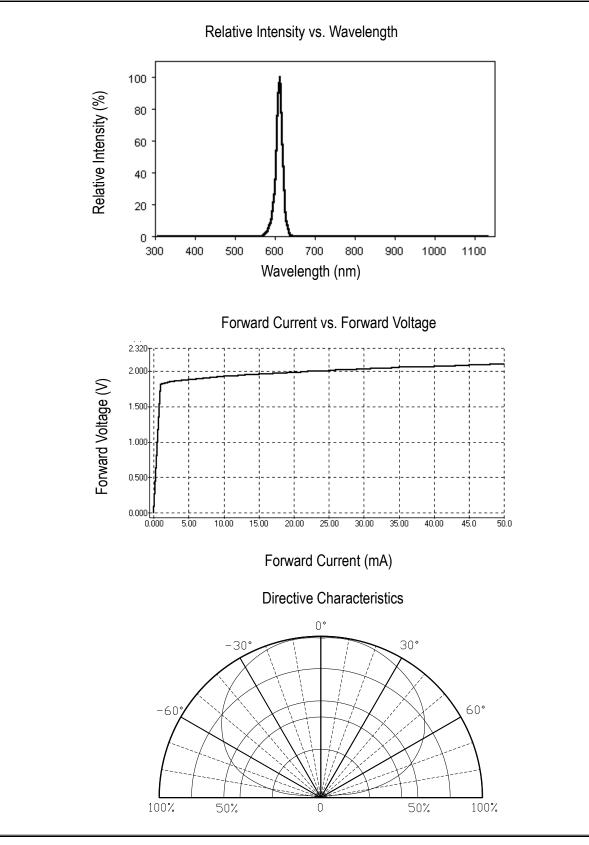
Emitted color

Part Number: N0A24S29

Absolute maximum ratings (T _A =25°C)						
Parameter	Symbol		Value			Unit
Forward current	lf		30		mA	
Reverse voltage	Vr		5 75 -40 ~+80			V
Power dissipation	Pd					mW
Operating temperature range	Тор)	°C
Storage temperature range	Tstę)	-40 ~+85)	°C
Peak pulsing current (1/8 duty f=1kHz)	lfp		125		mA	
Electro-optical characteristics						25°C)
Parameter	Test Condition	Symbol	Value			Unit
			Min	Тур	Max	
Wavelength at peak emission	lf=20mA	λpeak		610		nm
Spectral half bandwidth	lf=20mA	Δλ		17		nm
Dominant wavelength	lf=20mA	λdom	600		610	nm
Forward voltage	lf=20mA	Vf	1.7		2.5	V
Luminous intensity	lf=20mA	lv	80	130		mcd
Viewing angle at 50% Iv	lf=10mA	201/2		140		Deg
Reverse current	Vr=5V	lr			10	μA

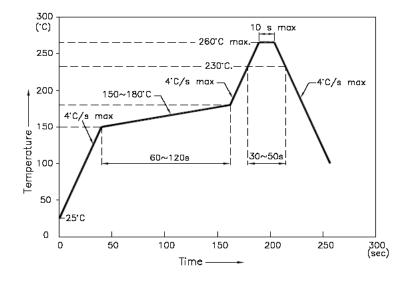
Part Number: N0A24S29

OPTICAL CHARACTERISTIC CURVES



Reflow Profile

Reflow Temp/Time



NOTES:

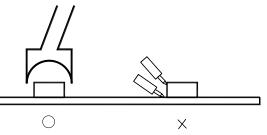
- 1. We recommend the reflow temperature 245 °C (±5 °C).the maximum soldering temperature should be limited to 260 °C.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

Rework

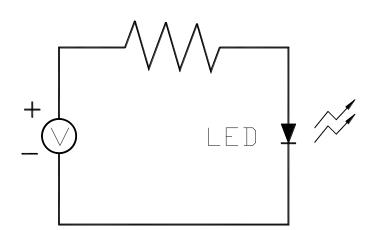
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

Test circuit



- Handling precautions
- 1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2.Storage
 - 2.1 It is recommended to store the products in the following conditions: Humidity: 60% R.H. Max.

Temperature : 5°C~30°C(41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at < 5°C~30°C and < 30% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at ≤20 R.H. with zip-lock sealed.

3.Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

- 3.1 60 \pm 3°C x(12~24hrs) and < 5%RH, taped reel type
- 3.2 100 \pm 3°C x(45min~1hr), bulk type
- $3.3 \ 130 \pm 3^{\circ}C \ x(15 \sim 30 min)$, bulk type

Test items and results of reliability

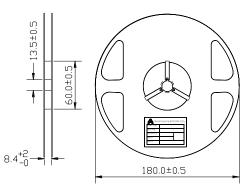
Туре	Test Item	Test Conditions	Note	Number of Damaged
	Temperature Cycle	-20°⊂ 30min ↑↓ 80°⊂ 30min	100 cycle	0/22
	Thermal Shock	-20°⊂ 15min ↑↓ 80°⊂ 15min	100 cycle	0/22
Environmental Sequence	High Humidity Heat Cycle	30°C⇔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
Envi	High Temperature Storage	T _a =80°C	1000 hrs	0/22
	Humidity Heat Storage	Ta=60°⊂ RH=90%	1000 hrs	0/22
	Low Temperature Storage	T₂=-30°C	1000 hrs	0/22
	Life Test	T _a =25°⊂ I _F =20mA	1000 hrs	0/22
Operation Sequence	High Humidity Heat Life Test	60°⊂ RH=90% I _F =10mA	500 hrs	0/22
	Low Temperature Life Test	T _a =-20°C I _F =20mA	1000 hrs	0/22

PACKAGING SPECIFICATIONS

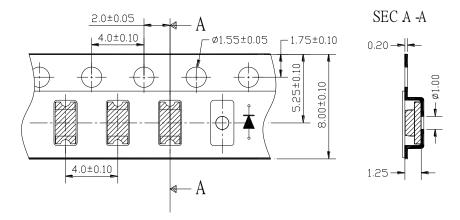
S150 Series SMD Chip LED Lamps Packaging Specifications

- Feeding Direction
- Feeding Direction

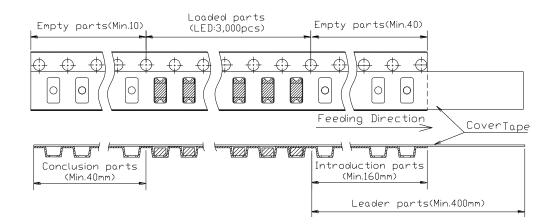




• Dimensions of Tape (Unit: mm)



• Arrangement of Tape



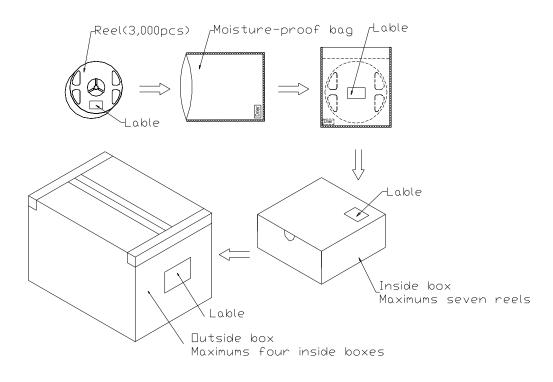
NOTES

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
- 4. 3,000 pcs/Reel

PACKAGING SPECIFICATIONS

S150 Series SMD Chip LED Lamps Packaging Specifications

• Packaging specifications



NOTES:

Reeled products (numbers of products are 3,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, Seven moisture-proof bag of maximums (total maximum number of products are 21,000pcs) packed in an inside box (size: about 238mm x about 194mm x about 102mm) and four inside boxes of maximums are put in the outside box (size: about 410mm x about 254mm x about 229mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the root the loading steps of outside box (cardboard box) has it to three steps.

SURFACE MOUNT LED LAMPS								
Part Number: N0A24S29								
Forward Voltage Rank Combination (IF=20mA)								
Rank	Min.		Max.	Unit				
	1.7		2.5	V				
Luminous Intensity Rank Combination (IF=20mA)								
Rank	Min.		Max.					
I	80		100					
J	J 100 125							
К	K 125		160					
L	160		200					
М	200							
Dominant wavelength Rank Combination (IF=20mA)								
Rank	Min.		Max.					
р	600		605					
q	605		610					
Group Name on	Label (Exam	ole DATA: 🗆 🛛	(q 20)					
DATA: 🛛 Kq 20	Vf(V)	lv (mcd)	λd (nm)	Test Condition				
□→K→q→20	1.7~2.5	125~160	25~160 605~610					

* NOTE:

1. The tolerance of luminous intensity (Iv)is $~\pm15\,\%$.

2. The tolerance of dominant wavelength is ± 1 nm.

3. This specification is preliminary.